

Abstract of the Disclosure

~~A method 3-D structures utilizing which are fabricated by gray-tone exposure of a class of thick negative photo-sensitized epoxy resists from the substrate side of a transparent substrate, using and development methods that rely upon a physical distinction between polymerized (solid) and unpolymerized (liquid) photoresist at elevated temperatures may be used to fabricate 3-D structures in the photo-sensitized epoxy. Such structures may exhibit smoothly-varying topographic features with thicknesses as great as 2 mm.~~